

AAEON is Bringing High-Speed 5G Capability to Edge Computing Platforms

EINDHOVEN, NETHERLANDS, December 7, 2021 /EINPresswire.com/ -- AAEON, a leading designer and manufacturer of industrial IoT and AI Edge solutions, has partnered with Fibocom to introduce high-speed 5G capability to their new edge computing platforms.

AAEON's latest innovations, [UP Xtreme i11](#) and [UP Squared Pro](#), are compatible with the [Fibocom FM150 5G module](#) via the M.2 3052 B Key slot. These edge platforms provide users and developers with ample performance and flexibility, while also leveraging the 5G network for faster speeds, higher bandwidth, and seamless connectivity in real time.

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AAEON is leading the way in developing edge platforms compatible with the 5G network. Our 5G-ready platforms deliver flexibility and expandability to deploy AI Edge platforms wherever they are needed.”

Victor Lai, Managing Director of AAEON Technology Europe



UP Xtreme i11 and UP Squared Pro are powerful computing platforms built for industrial applications to scale Industry 4.0 initiatives. UP Xtreme i11 is powered by the latest 11th Generation Intel® Core™ Processors, which can clock up to 4.4 GHz with only 28 watts TDP and 15 watts cTDP. For even more power-efficient performance at the edge, UP Squared Pro features the Intel Atom® E3950 processor series (including Intel® Pentium® and Intel® Celeron®), which runs at speeds up to 2.5 GHz.

The Fibocom FM150 5G module is globally certified for North America, Asia (excluding China), Europe, and Australia. Supports the 5G NR Sub-6 band, and supports

the 5G standalone (SA) network and non-standalone (NSA) network architectures, eliminating customers' investment concerns in the initial stage of 5G construction and responding to the commercial demand of rapid landing.

“AAEON is leading the way in developing edge platforms compatible with the next generation 5G network support. We are excited to collaborate with Fibocom to launch our line of 5G-ready platforms. Together, we deliver flexibility and expandability to deploy AI Edge computing and IoT/AIoT networks wherever they are needed,” said Victor Lai, Managing Director of AAEON Technology Europe.

More AAEON 5G-ready platform for industrial usage: BOXER-6643-TGU, MAX-Q470A, FWS-2365, VPC-5620S, and VPC-3350S

The UP Xtreme i11 and UP Squared Pro are available for purchase now with the Fibocom FM150 5G module. For more information regarding AAEON products and services, please contact us at Sales@aaeon.eu.

[Media Kit Download]
https://solutions.aaeon.com/5G_Ready_Platforms_and_Fibocom_5G_Module_PR_Media_Kit.zip



Fibocom 5G Module and Accessories

Product	Processor	Memory	Storage	Ethernet	Display	Audio	USB	Expansion	Power
UP Xtreme i11	Intel 11th Generation Core Processor	2x DDR4 8-channel SO-DIMM VERTICAL, MAX 64GB (8 x 32GB/16 x 32GB/16 x 32GB/16 x 32GB)	1x SATA 3.0 connector with power connector (1x M.2 2280 M-key optional), PCIe (1) NVMe	1x 10Gb LAN (2110), 1x 2.5Gb LAN (2250)	1x HDMI 2.0b, 1x DP - 1x USB Type-C (13 DP - 4x USB 4.0), 1x eDP	1x HDMI Audio, 1x DP Audio, Speaker/Codec for Audio Out/Mic In, USB	4x USB 3.2 Gen 2 Type A, 1x USB 4.0 Type C	2x RS232C/422/485, M.2 2280 1 Key, M.2 2280 M Key, M.2 3002 B Key, PD-04A (hotplug board accessory required)	12V DC-IN
UP Squared Pro	Intel 7th Generation Core Processor	2GB 4GB 8GB	32GB 64GB	2x Intel® I210 AT support T30	1x HDMI 1.4, 1x DP 1.2	Audio Jack In-out	3x USB 3.0 Type A, 1x USB 3.0 OTG	2x RS232C/422/485, 1x SATA III, M.2 2280 1 Key, M.2 2280 M Key, M.2 3002/3002 B Key (optional)	12-24V DC-IN
BOXER-6643-TGU	Intel 11th Generation Core Processor	2x DDR4 SO-DIMM, up to 64GB	Support High Speed NVMe storage (M.2 2280, 2.5" SATA, SSD/HDD bay)	1x 10Gb LAN (2110), 1x 2.5Gb LAN (2250)	2x HDMI 1.4	Line Out	4x USB 3.2 Gen 2 Type A	2x RS-232C/422/485, M.2 2280 M Key, M.2 3002 B Key, Full Size Mini Card (mSATA/PCh Auto Switch)	Wide Range 9-30V DC Input
MAX-Q470A	Intel 10th Generation Core Processor	4x DIMM, DDR4 (2x 32GB/2x 16GB), max. 128GB (not ECC, unbuffered memory, Dual-channel memory architecture)	4x SATA III (6.0Gb/s) ports, support RAID 0/1/5/10, 1x M.2 2280/2242 M-key (PCIe)	1x Intel® I210-LM support Intel® AMT, 12GbE, 1x Intel® I211AT, 2x RJ45	3x HDMI (1x HDMI 2.0 & 2x HDMI 1.4), 1x VGA, 1x Speaker/Headset Line-out (external), 1x AUP (internal)	2x Audio Jack: Line In, Mic In, Line out, 1x Speaker/Headset Line-out (external), 1x AUP (internal)	2x USB 3.2 Gen 2 Type A, 4x USB 3.0 Gen 1 Type A	1x D0 - D20M, 2x RS-232C, 1x Micro SD Card Slot, M.2 2280 1 Key (PCIe), M.2 2280/2242 M-key (PCIe), M.2 2280/2242 B-key (PCIe), M.2 3002 (PCIe) B-key, PCh 3.0 (4x), PCh 3.0 (4x) (2 lanes), PCh 3.0 (4x) (2 lanes)	1x 24-pin ATX connector, 1x 8-pin (24 pin), ATX 12V Power connector
UP-9620B	Intel 8th Generation Core Processor	DDR4 2GB pin SO-DIMM, up to 64GB	2x 2.5" SSD	1x Intel® I211 (GigE), 1x PCIe ports	1x HDMI 1.4, 1x DP 1.2	Audio Jack Line-Out/Mic In	4x USB 3.2 Gen 1 Type A	2x RS-232C/422/485, M.2 2280 M Key (USB-PCh), support H/ME PCh (M.2), Full Size (USB+PCIe), mPCIe Full Size (USB+SATA) (only SATA)	12-24V DC with power ignition
FWS-2365	Intel Atom C2000 Series	2x DDR4 SO-DIMM socket	Optional 16GB mMMC, 2x SATA III PWT, 1x 2.5" 3.5" HDD Bay	1x Intel® I211 (GigE) ports, 1x 10Gb SFP+, 4x 10Gb SFP+ (4 cores only support 2 ports)	Console port	N/A	2x USB 3.0 Type A (1 Port only support USB 2.0)	2x RS-232C/422/485, PCh, Mini Card slot (Full-Size, PCh - USB2.0) with SIM, M.2 3002 B Key (ESD) with SIM slot	12V DC-IN
VPC-3350S	Intel 7th Generation Core Processor	DDR3L 2GB pin SO-DIMM, up to 8GB	1x 2.5" SSD	Intel® I211 (GigE) (210)	1x HDMI 1.4, 1x DP 1.2	Audio Jack Line-Out/Mic In	2x USB 3.2 Gen 1 Type A	2x RS-232C/422/485, 2x Mini Card slot (ESD 2.0 - PCh, Mini Card), or 1x 1.5" slot on the vendor configuration, CMBus on in-vehicle configuration	DC 12-24V, or DC 3-24V with power ignition on in-vehicle configuration

AAEON 5G ready platform details

About AAEON and UP Bridge the Gap

Established in 1992, AAEON is one of the leading designers and manufacturers of industrial IoT and AI Edge solutions. With continual innovation as a core value, AAEON provides reliable, high-quality computing platforms including industrial motherboards and systems, rugged tablets, embedded AI Edge systems, uCPE network appliances, and LoRaWAN/WWAN solutions.

UP Bridge the Gap is a brand founded by AAEON Technology Europe in 2015. The UP team aims to bring innovation in technology, business models, and integrated solutions. The UP team collaborates with market leaders in different vertical markets to develop integrated solutions and build a large online community to work closely with developers.

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